

Kindly enter the following amendments:

**IN THE CLAIMS:**

Please amend the Claims as follows:

1. (Twice Amended) An RF package comprising:

a multilayered dielectric substrate <sup>comprising</sup> [on which] first and second dielectric substrates [are formed] said multilayered dielectric substrate having a cavity in the second dielectric substrate where a semiconductor element is to be mounted on the first dielectric substrate;

a feed-through for connecting an inside and outside of said cavity and comprised of a coplanar line <sup>disposed</sup> [formed] on said first dielectric substrate and an inner layer line <sup>disposed</sup> [formed] on the first dielectric substrate <sup>and</sup> obtained by <sup>disposing</sup> [forming] said second dielectric substrate on said coplanar line, said coplanar line and said inner layer line sharing a signal conductor <sup>disposed</sup> [formed] on the first dielectric substrate; [and]

metal members <sup>disposed</sup> [formed] at a connection interface between said coplanar line and said inner layer line on two sides of said signal conductor, and connecting ground conductors of the coplanar line and the inner layer line on the first dielectric substrate to a top surface of the second dielectric substrate at an edge of the second dielectric; and

a plurality of first via holes <sup>disposed</sup> [formed] in said first dielectric substrate and a plurality of second via holes <sup>disposed</sup> [formed] in said second dielectric substrate.

2. (Amended) A package according to claim 1, further comprising:

first ground conductors <sup>disposed</sup> ~~formed~~ on an upper surface of said first dielectric substrate and arranged on two sides of said signal conductor to be away from each other at a predetermined distance; <sup>how relate to d1</sup>

a second ground conductor <sup>disposed</sup> ~~formed~~ on said second dielectric substrate; and

[a] said plurality of [first] second via holes <sup>disposed</sup> ~~formed~~ in said second dielectric substrate to connect said first and second ground conductors to each other at positions away from said connection interface between said coplanar line and said inner layer line.

3. (Amended) A package according to claim 2, wherein a distance  $\lambda$  <sup>from</sup> ~~between~~ said connection interface between said coplanar line and said inner layer line <sup>to</sup> ~~and~~ a center of one of said [first] second via holes which is at an end nearest to said connection interface is represented by

$$\lambda < \frac{c}{2f\sqrt{\epsilon_r}}$$

where c, f, and  $\epsilon_r$  respectively indicate a speed of light, a signal frequency, and a specific dielectric constant of said dielectric substrate.

4. (Amended) A package according to claim 2, wherein

<sup>plurality of</sup>  
said [first] second via holes are arranged on two sides of said signal conductor at a  
predetermined pitch, and

a pitch  $\lambda_{p2}$  of said [first] <sup>plural</sup> second via holes in a signal propagating direction is represented

by

$$\lambda_{p2} < \frac{c}{2f\sqrt{\epsilon_r}}$$

where c, f, and  $\epsilon_r$  respectively indicate a speed of light, a signal frequency, and a specific dielectric constant of said dielectric substrate.

5. (Amended) A package according to claim 4, wherein a pitch w of said [first] second via hole in a direction perpendicular to the signal propagating direction is indicated by

$$W < \frac{c}{2f\sqrt{\epsilon_r}}$$

6. (Amended) A package according to claim 4, further comprising:

a third ground conductor formed on a lower surface of said first dielectric substrate; and

[second] <sup>plurality of</sup> said first via holes <sup>disposed</sup> formed in said first dielectric substrate to connect said first and third ground conductors to each other, said [second] first via holes being arranged on two sides of said signal conductor at a predetermined pitch.

7. (Amended) A package according to claim 6, wherein a pitch  $\lambda_{p1}$  of said [second] first via holes in the signal propagating direction is represented by <sup>V</sup> plan of

$$\lambda_{p1} < \frac{c}{2f \sqrt{\frac{\epsilon_r + 1}{2}}}$$

8. (Amended) A package according to claim 2, wherein said metal members have ends on a signal conductor side that are aligned with ends of said [first] second via holes on the signal conductor side.

11. (Amended) A package according to claim 1, wherein said metal members are semi-cylindrical metal electrodes having an edge at said connection interface which does not extend beyond said connection interface.

12. (Amended) A package according to claim 1, wherein said metal members are metal plates projecting from a side of said second dielectric substrate extending beyond said connection interface in a direction toward said coplanar line.

Please add the following new Claims:

14. A package according to claim 1, wherein edges of said metal members at said connection interface measuring a first length at said connection interface, said first length being larger than a diameter of at least one of: a portion of said first via holes in said first dielectric substrate, and a portion of said second via holes in said second dielectric substrate.